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RENESAS SEMICONDUCTOR RELIABILITY REPORT

DEVICE: R1RP0416DSB-0PR#D1

APPLICATION: Standard

Quality Assurance Div.
Renesas Electronics Corporation

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Reliability test result

Test Items	Reference	Test Conditions	Results Reject/Size
High Temperature Operating Life	JESD22-A108	T _a = 125 °C, V _{cc} max, 1000 h	0/231
Low Temperature Operating Life	JESD22-A108	T _j = -40 °C, V _{cc} max, 1000 h	0/32
High Temperature Storage Life	JESD22-A103	T _a = 150 °C, 1000 h	0/75
Temperature Humidity Bias (HAST)	JESD22-A110	T _a = 130 °C, 85% RH, V _{cc} max, 96 h	0/75
Temperature Cycling	JESD22-A104	T _a = -65 °C to +150 °C, 300 cycles	0/75
Unbiased Temperature Humidity (Unbiased HAST)	JESD22-A118	T _a = 130 °C, 85%RH, 96h	0/75
Resistance to Soldering Heat	JESD22-A113, J-STD-020	Bake:125 °C, 24 h Moisture Soak: 30 °C 70% RH, 192h (JEDEC-MSL3 Equivalent) Reflow: 260 °C peak, 255 °C 30 s, 3 times	0/33
Solderability	J-STD-002	245 °C, 5 s 95% solder coverage minimum	0/5
Electrostatic discharge (HBM Method)	JS-001	C = 100 pF, R = 1.5 kΩ, ±1000 V	0/3
Electrostatic discharge (CDM Method)	JESD22-C101	±500 V	0/3
Latch-up (I-Test)	JESD78	±150 mA	0/3
Tin Whisker Acceptance (Temperature Humidity Storage)	JESD22-A121	T _a = 30 °C, 60% RH, 4000 h	0/3
Tin Whisker Acceptance (High Temperature Humidity Storage)	JESD22-A121	T _a = 55 °C, 85% RH, 4000 h	0/3
Tin Whisker Acceptance (Temperature Cycling)	JESD22-A121	T _a = -40/85 °C, 1500 cycles	0/3
Estimated Failure Rate	-	8.1 FIT or less Prerequisites: T _a = 55 °C, E _a = 0.5 eV, C.L. = 60%	
System Soft Error Testing (SSER)	JESD89-1	218 FIT/Mbit or less (no error) Prerequisites: C.L. = 60%	

Reliability test results may include data from family representative products. MSL Preconditioning was performed prior to HAST, Temperature Cycling and Unbiased HAST.

The Criteria shall follow the electrical characteristics in Specifications, except for Solderability and SSER.

Preconditioning Details: Bake (125 °C, 24 h) -> Moisture Soak (30 °C 70% RH, 192 h) -> Reflow (260 °C peak, 3 times)